

**A. Amendments To The Claims**

Please amend the claims as follows:

1. (Currently amended) A method for fabricating an electrical circuit, comprising the steps of:

depositing a layer of a first conductive material onto a surface of a flexible substrate, wherein said layer of a first conductive material is substantially transparent and wherein at least a portion of said substrate is translucent or transparent;

depositing a layer of a second conductive material onto said layer of a first conductive material;

selectively etching a portion of said layer of a second conductive material; and

selectively etching a portion of said layer of a first conductive material.

2. (Canceled)

3. (Original) The method of claim 1 wherein said first conductive material is indium tin oxide.

4. (Currently amended) The method of claim 1 wherein said second conductive material is ~~copper~~ a conventional conductive material.

5. (Original) The method of claim 4 further comprising the step of electrically connecting an electrical component to said second conductive material.

6. (Original) The method of claim 5 wherein said step of electrically connecting said electrical component to said second conductive material comprises soldering said electrical component to said second conductive material.

7. (Previously presented) The method of claim 1 further comprising the step of depositing an additional layer of conductive material onto said layer of second conductive material.

8. (Original) The method of claim 7 wherein said layer of second conductive material is substantially transparent.

9. (Original) The method of claim 7 wherein said second conductive material is an oxide of niobium.

10. (Currently amended) The method of ~~claim 7~~ claim 8 wherein said ~~third material is copper~~ additional layer of conductive material comprises a conventional conductive material.

11. (Previously presented) The method of claim 7 further comprising the step of electrically connecting an electrical component to said additional layer of conductive material.

12. (Previously presented) The method of claim 11 wherein said step of electrically connecting said electrical component to said additional layer of conductive material comprises soldering said electrical component to said additional layer of conductive material.

13. (Previously presented) The method of claim 1 wherein at least one of said steps of depositing occurs in a substantial vacuum.

14. (Original) The method of claim 1 further comprising the step of pretreating said surface of said substrate to enhance adhesion of said layer of first conductive material to said substrate.

15-18. (Canceled)

19. (Previously presented) A method for fabricating an electrical circuit, comprising the steps of:

depositing a layer of a first conductive material onto a first surface of a substrate;  
depositing a layer of a second conductive material onto a second surface of said substrate;

selectively etching a portion of said layer of a first conductive material;

selectively etching a portion of said layer of a second conductive material;

perforating said substrate at a predetermined location; and

electrically coupling said layer of a first conductive material with said layer of a second conductive material via said perforation.

20-25. (Canceled)

26. (Previously presented) The method of claim 1 further comprising the step of patterning said layer of a second conductive material to define said portion of said layer of a second conductive material to be etched in connection with said step of etching said layer of a second conductive material.

27. (Previously presented) The method of claim 26 further comprising the step of patterning said layer of a first conductive material to define said portion of said layer of a first conductive material to be etched in connection with said step of etching said layer of a first conductive material.

28. (Previously presented) The method of claim 1 further comprising the step of patterning said layer of a first conductive material to define said portion of said layer of a first conductive material to be etched in connection with said step of etching said layer of a first conductive material.

29-30. (Canceled)

31. (Previously presented) The method of claim 1 wherein said step of selectively etching said layer of a second conductive material is performed using an etchant that is selected to etch said layer of a second conductive material and to not substantially etch said layer of a first conductive material.

32-35. (Canceled)

36. (Previously presented) A method for fabricating an electrical circuit, comprising the steps of:

depositing a layer of a first conductive material onto a surface of a substrate, either directly or in connection with an intermediary layer between said layer of a first conductive material and said surface of a substrate;

depositing a layer of a second conductive material onto said layer of a first conductive material in connection with an interfacial layer deposited between said layer of a second conductive material and said layer of a first conductive material;

selectively etching a portion of said layer of a second conductive material;

selectively etching a portion of said interfacial layer; and

selectively etching a portion of said layer of a first conductive material.

37-40. (Canceled)

41. (Currently amended) The method of claim 36 wherein said step of etching said layer of a second conductive material is performed using an etchant that etches said layer of a second conductive material ~~at a first rate~~ and that does not substantially etch said layer of a first conductive material.

42-44. (Canceled)

45. (Previously presented) The method of claim 1 wherein said substrate is supplied to and taken up from a support ~~drum~~ that supports said substrate during said steps of depositing.

46. (Currently amended) The method of ~~claim 7~~ claim 10 wherein said additional layer of conductive material comprises ~~a third conductive material~~ copper.

47. (New) The method of claim 4 wherein said second conductive material is copper.

48. (New) The method of claim 1 wherein said steps of selectively etching occur after said steps of depositing.

49. (New) The method of claim 48 further comprising the steps of:  
providing said flexible substrate on a supply roll; and  
unrolling said flexible substrate from said supply roll;  
wherein said steps of depositing said layer of a first conductive material onto said flexible substrate and depositing said layer of a second conductive material onto said layer of a first conductive material are conducted on a continuous basis.

50. (New) The method of claim 49 further comprising the step of rolling said flexible substrate with said layers of conductive material applied thereto onto a take-up roll.

51. (New) A process for bulk fabrication of an electrical circuit platform, comprising the steps of:

providing a flexible substrate in bulk form;  
feeding said flexible substrate through an apparatus adapted to deposit conductive materials thereon;

depositing a layer of a first conductive material onto said flexible substrate; and  
depositing a layer of a second conductive material onto said layer of a first conductive material;

wherein said layer of a first conductive material is transparent, and  
wherein said steps of depositing are performed on a substantially continuous basis or an indexed basis.

52. (New) The process of claim 51 wherein said apparatus comprises a drum, said drum supporting said flexible substrate during said steps of depositing.

53. (New) The process of claim 51 further comprising the step of rolling said flexible substrate with said layers of conductive material applied thereto onto a take-up roll.

54. (New) The process of claim 51 wherein said steps of depositing are performed in a vacuum chamber.

55. (New) The process of claim 51 wherein said second conductive material is a conventional conductive material.

56. (New) The process of claim 51 further comprising the step of depositing an additional layer of conductive material onto said layer of a second conductive material.

57. (New) The process of claim 56 wherein said layer of a second conductive material is substantially transparent.

58. (New) The process of claim 57 wherein said additional layer of conductive material comprises a conventional conductive material.

59. (New) The process of claim 58 wherein said additional layer of conductive material comprises copper.

60. (New) The method of claim 51 wherein said steps of depositing are performed on a substantially continuous basis.

61. (New) The method of claim 36 wherein said layer of a first conductive material is substantially transparent.

62. (New) The method of claim 19 wherein said layer of a first conductive material is substantially transparent.

63. (New) The method of claim 62 further comprising the step of depositing an additional layer of conductive material on said layer of a second conductive material.